

# Newsletter n°14 – February 2015

Set Insights

#### Our Sales Team reinforced and fully at your service!

**SET** has restructured and reinforced strongly its Sales Team in the past few months. Of course, renowned contact people from SET like Jean-Stephane Mottet - Sales Director -, Denis Rossignol - After-Sales Services Manager -, Virginie Boimond – Service Assistant - and Catherine Guebey - Sales Administrator-, are still there

and fully dedicated to customers, but new people have joined our Team. First of all, Mrs. Caroline Avrillier has joined SET in 2014 as Sales Manager and will be mainly in charge of selling our machines in Europe with, in some countries, the support of our existing agents.

Mr. Frederic Montis also joined us beginning of 2015 as Sales Manager too. He will develop our sales in the rest of the world and will manage our channel of agents.

These two new sales people will allow Jean-Stephane to be more dedicated to global sales management and technical support to sales. All our Team can operate all around the world and is at your service. Feel free to contact us for any support, needs or requests!



## ACCµRA<sup>™</sup>100: "SET" a new frontier to your limits!



The ACCµRA<sup>™</sup>100 is a semi-automatic flip-chip bonder that allows ±0.5 µm post-bonding accuracy. Its flexibility makes it ideal for developing a wide range of applications (i.e. laser and photo diodes, LEDs, chip-to-wafer, chip-to-chip, MEMS...). ACCµRA<sup>™</sup>100 combines high precision, accessibility, quick set-up of new applications, small footprint and compact design, high bonding force and cost-effectiveness. ACCµRA<sup>™</sup>100 is a table top machine with a user-friendly Windows interface and touch-screen. It is the perfect equipment for universities and R&D institutes.

Contact your local agent or SET for more info!

#### First ever delivery of the ACCµRA<sup>™</sup>100 at the University of Geneva / CERN

SET is pleased to announce the **first ever delivery of the ACCµRA<sup>TM</sup>100** to the University of Geneva (Switzerland) in collaboration with CERN (European Organization for Nuclear Research). This delivery will take place in June this year and will be an opportunity for both "Geneva University – CERN venture" and SET for a special and long-term technical partnership.

SET is used to have close partnerships with its customers but, in this special case as it is the first ACC $\mu$ RA<sup>TM</sup> 100 delivery, SET will share all its knowledge and support with the University and in return the University will share all its technical results with SET and will help SET with the final fine-tuning of the machine.





## SET equipment: for infrared sensors, but not only, new possibilities ahead!

SET equipment are well-known for infrared sensors mounting, sector where our machines have established world best class standards and our know-how is recognized, but **new opportunities** can also be targeted **such** as LEDs, MEMS, optoelectronics, 3D packaging, RF applications...

As you can see on pictures and examples below (from left to right: Optical Bench for Photonics Packaging,



MEMS for Scanning Electron Microscope and Multi-Chip Module), SET machines can work easily, with a total accuracy and repeatability for all kinds of applications. Our machines are designed and settled-up to fit with all specifications, requirements and/or constraints of these sectors.

## **Exhibitions and Conferences:** when and where meeting **SET** in 2015

**SET** already attended to **Semicon Korea** this year (from Feb. 3<sup>rd</sup> to 6<sup>th</sup>) with the kind and appreciated support of our local agent Woowon. This exhibition was a great success to us and we look forward to developing our business in Korea !

We were also present to **3D TSV Summit** in Grenoble, France, mid of January.

In addition SET will take part, with the kind collaboration of our local agents, to the following forthcoming fairs and congresses:

- **MicroTech** (Didcot UK) on March 5<sup>th</sup>
- Semicon China (Shanghai China) from March 17<sup>th</sup> to 19<sup>th</sup>
- **MiNaPAD** (Grenoble France) from April 21<sup>st</sup> to 23<sup>rd</sup>
- Semicon South Asia (Penang Malaysia) from April 22<sup>nd</sup> to 24<sup>th</sup>
- ECTC (San Diego USA) from May 26<sup>th</sup> to 29<sup>th</sup>
- **Semicon West** (San Francisco USA) from July 14<sup>th</sup> to 16<sup>th</sup>
- Semicon Taiwan (Taipei) from September 2<sup>nd</sup> to 4th



We will present our latest machines, developments and technical support. We will advertise soon about our future participations to exhibitions for the second part of 2015. Save the date and join us there!

## **KADETT demo machine:** A good opportunity for investing!



SET is proposing an exceptional offer on a **KADETT** demo machine: a fully operational machine at a very attractive cost!

The KADETT is an open platform that guarantees  $\pm$  3 µm post-bond accuracy for flip-chip applications. Its flexibility allows a very quick and easy setup of applications. The KADETT is suitable for universities, R&D institutes and companies which want to invest in basic but efficient, accurate, easy to use and lifelong equipment.

Our demo machine is well maintained and configured with heating chucks for thermo compression and reflow processes.

Do not hesitate to contact SET directly for more information and an appropriate offer!

#### **1975** - **2015**: 40 years for SET, 40 years with you!



As you may have understood with the special logo stamped on this Newsletter, SET is proud to celebrate this year **40 years of existence**, 40 years of experience and 40 years with you!

2015 will be a full year of celebrations for SET and we will come back to you soon with more details and more events to come!...